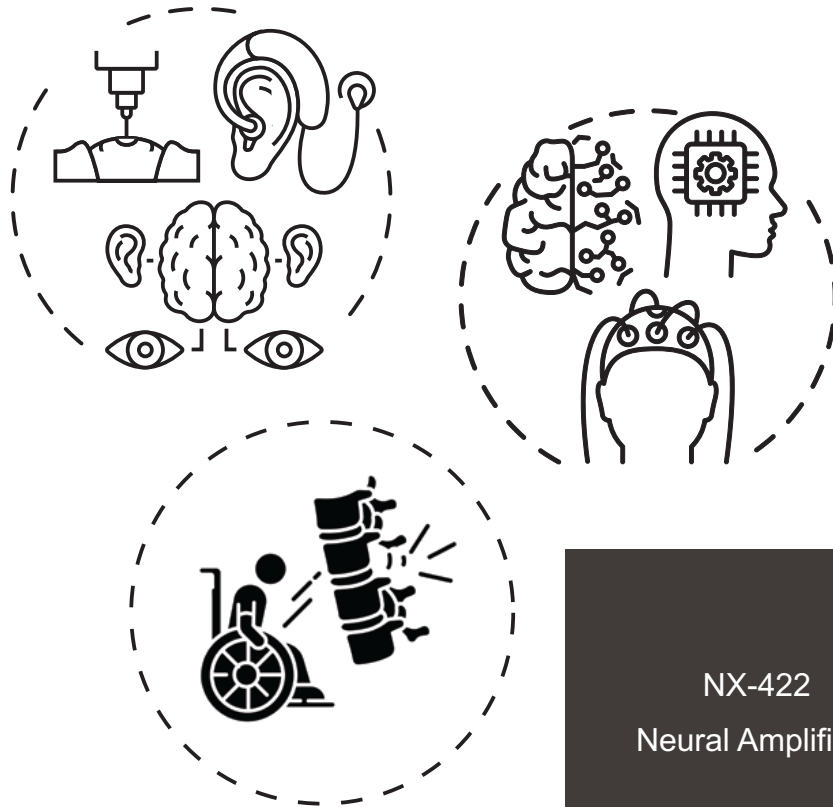




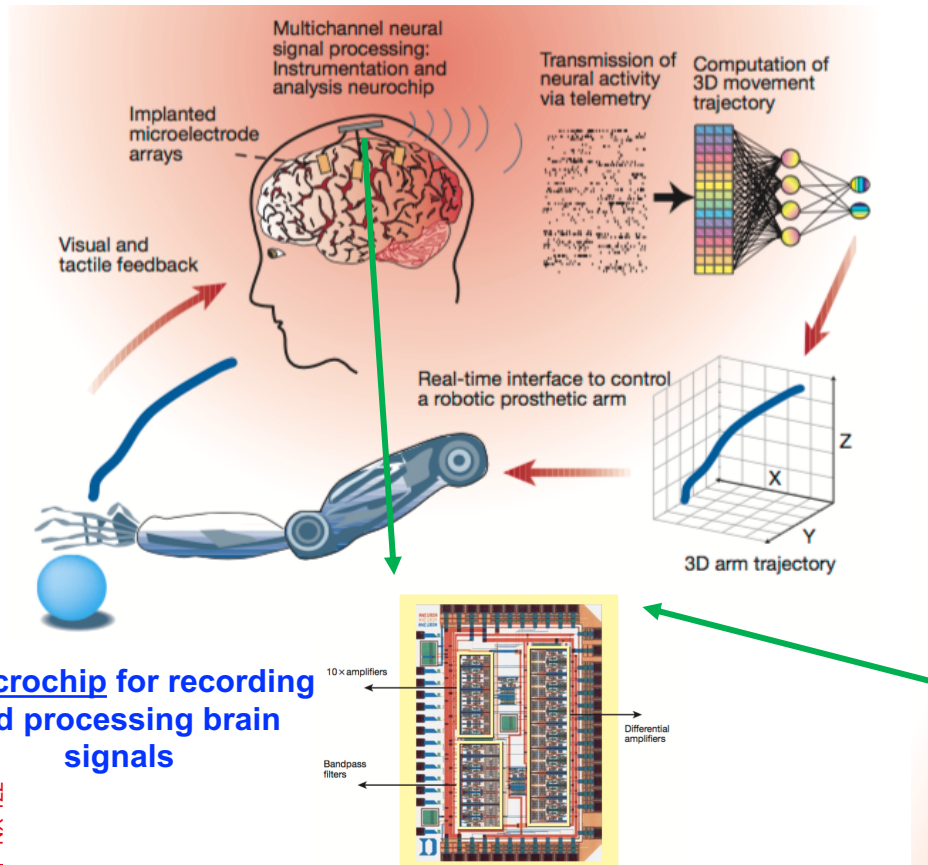
Neural Interfaces

NX-422
Neural Amplifiers

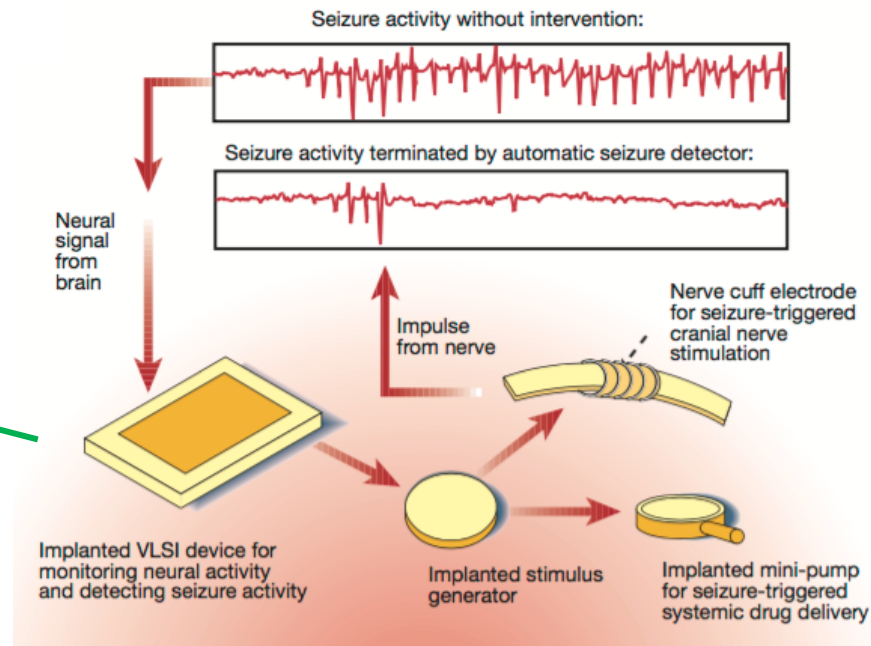
Mahsa Shoaran
IEM and Neuro-X Institutes

Recap: Two Types of Neural Interfaces

1) Brain-Machine Interface



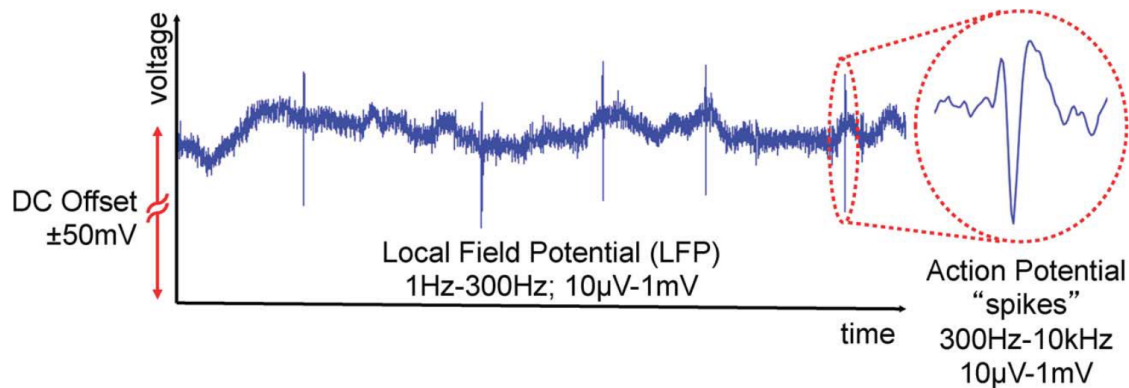
2) Closed-loop Neuromodulation



A microchip for recording and processing brain signals

Recap: Local Field Potentials (LFPs)

- < 300 Hz : **Local Field Potentials (LFP)**
- $300 - 10\text{kHz}$: **Single-Unit Activity (AP or “spikes”)**
- Local Field Potential (LFP) – electrical activity of all cells **averaged over some spatial neighborhood**
- **High-pass filtering** gives **spikes**

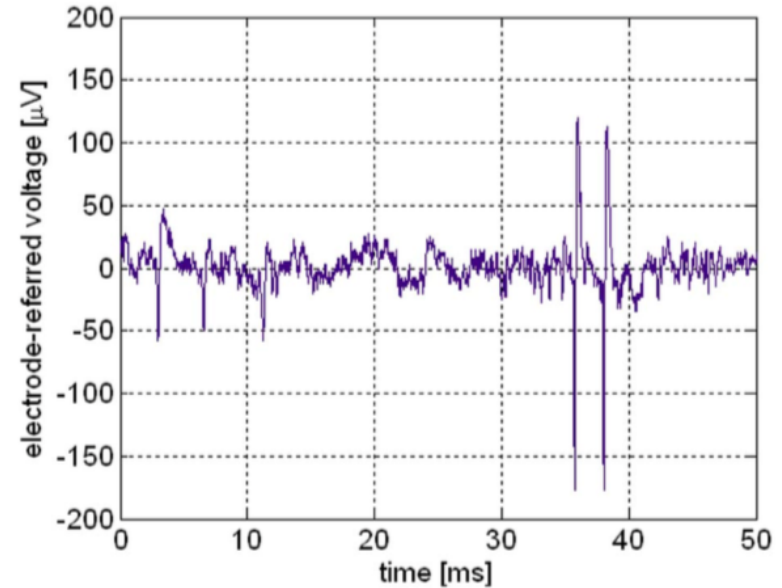
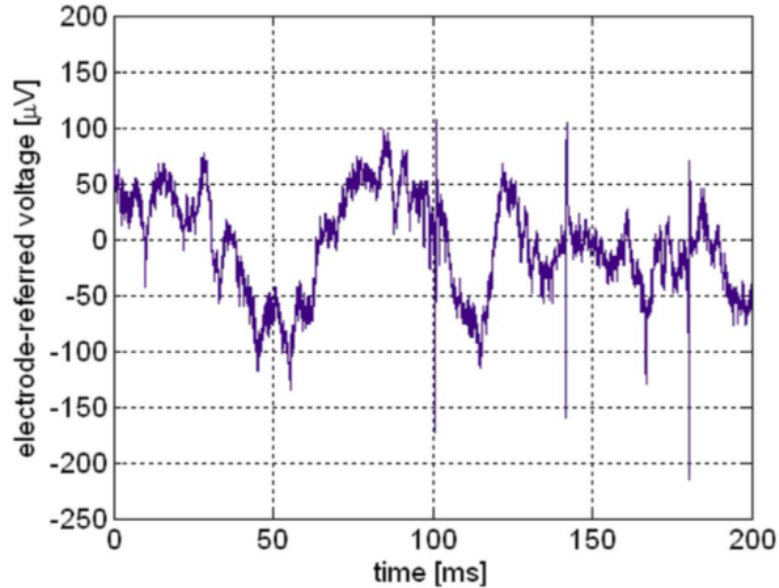


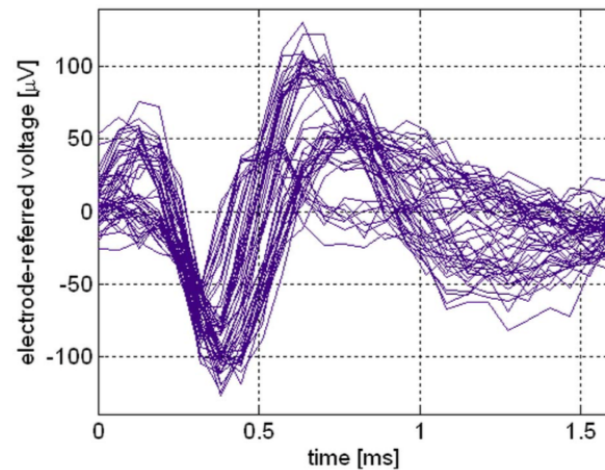
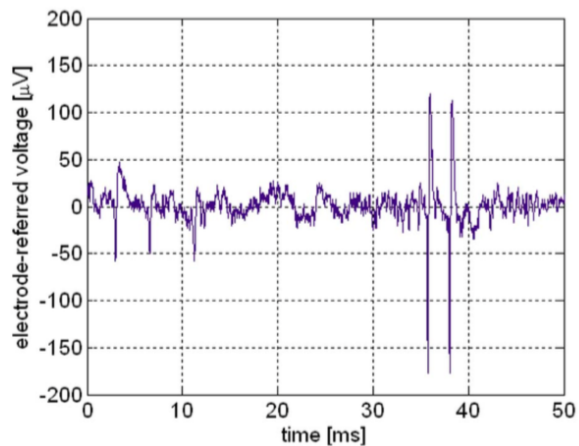
High-pass filter at 300Hz

Both Spikes and LFPs

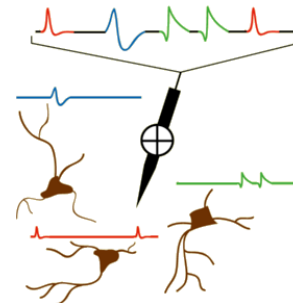
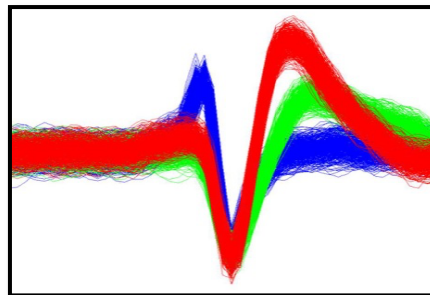


Spikes

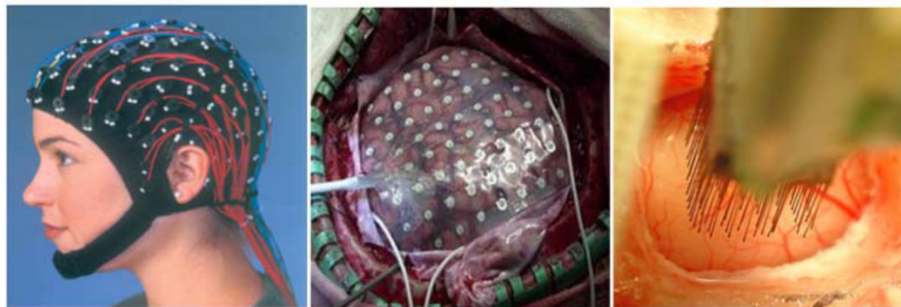




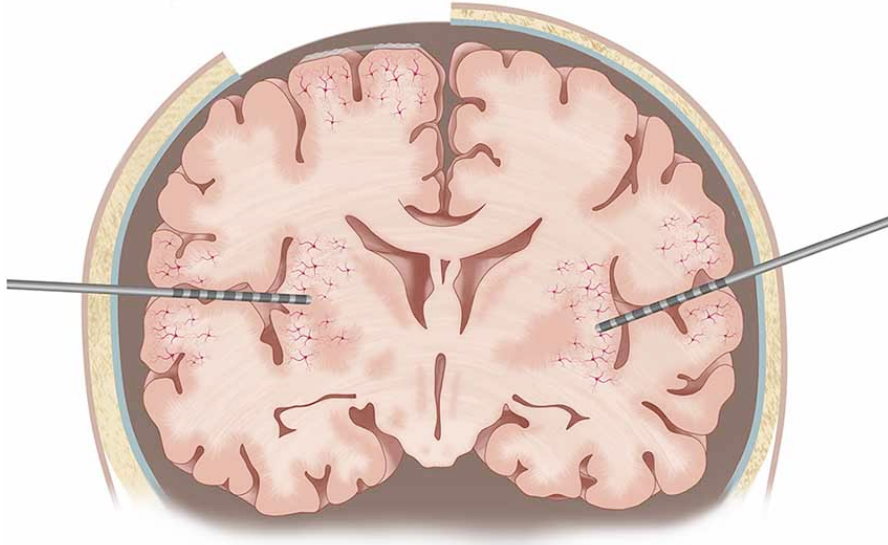
Spike Sorting



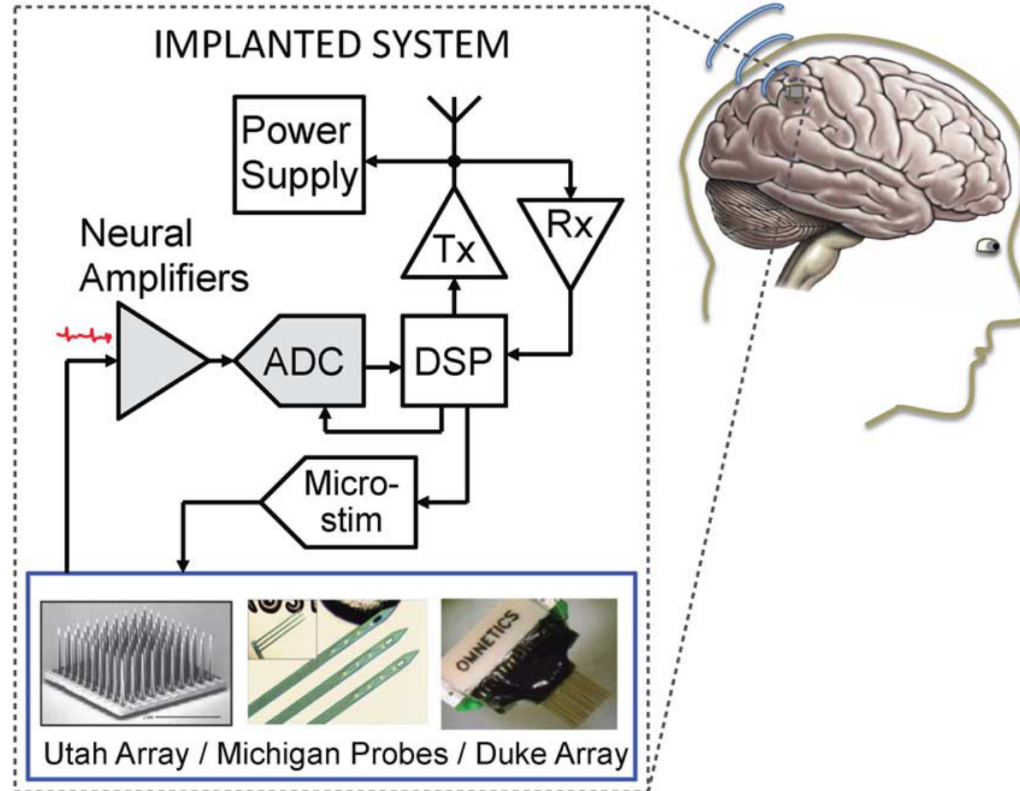
Comparison: EEG, ECoG, LFP, and AP



	EEG	ECoG	LFP	AP
Bandwidth	0.5-50Hz	1-500Hz	1-500Hz	250-10kHz
Amplitude	1-50 μ V	1-500 μ V	10 μ -1mV	10 μ -1mV
Spacing	3cm	0.2-10mm	0.1-1mm	0.1-1mm
Invasive	No	Craniotomy, no neural damage	Craniotomy, neural damage	Craniotomy, neural damage
Area Coverage	Whole Brain	$\sim \text{cm}^2$, whole brain	$\sim \text{mm}^2$	$\sim \text{mm}^2$
Stability	Decades	Decades	Years	Months

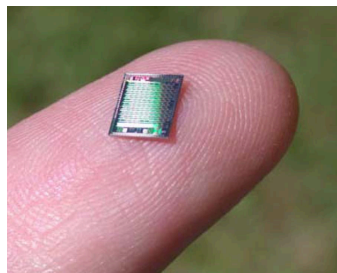


Circuit Block Diagram of a Neural Interface

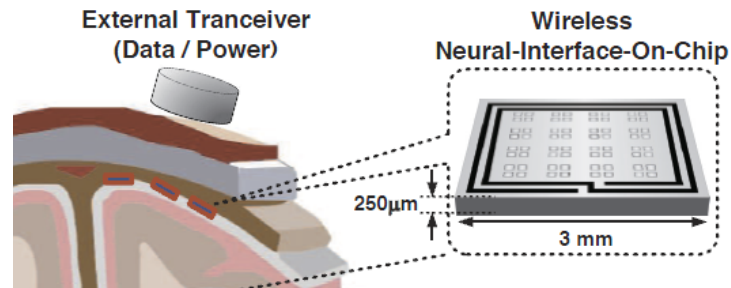
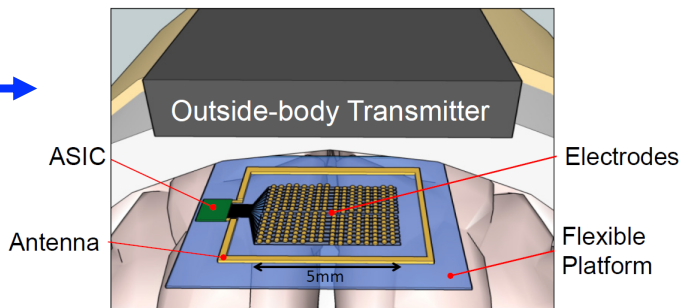


Cortical and Intracortical Systems

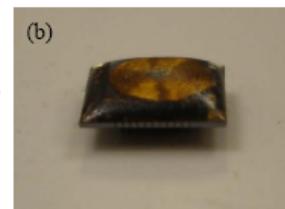
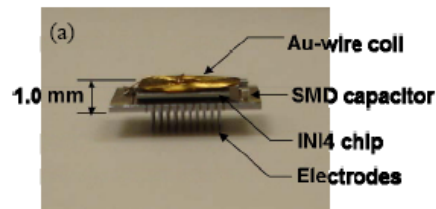
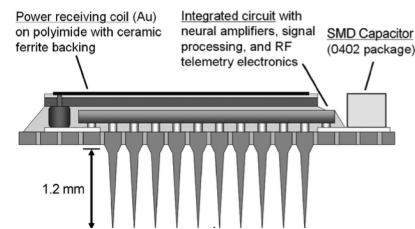
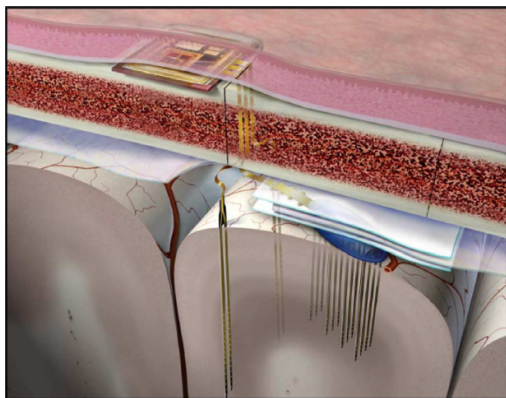
IC or ASIC



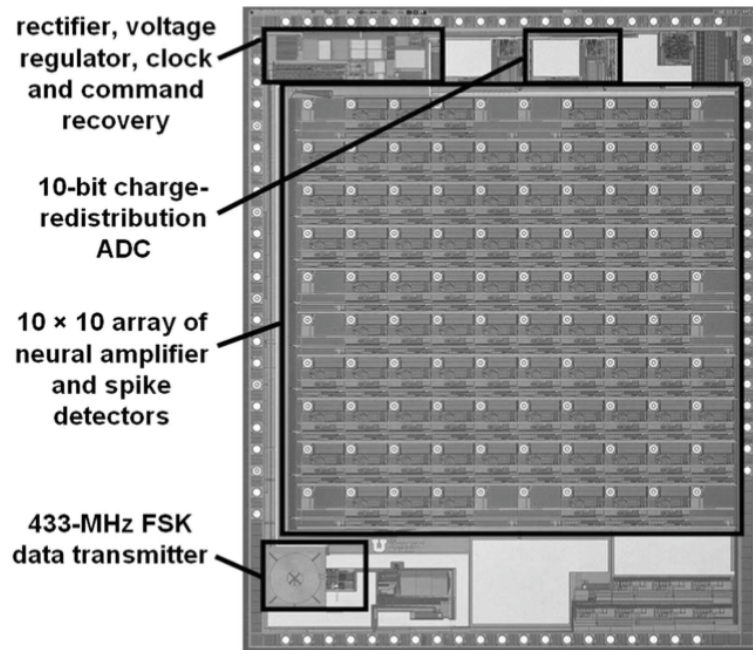
Cortical or ECoG-based systems



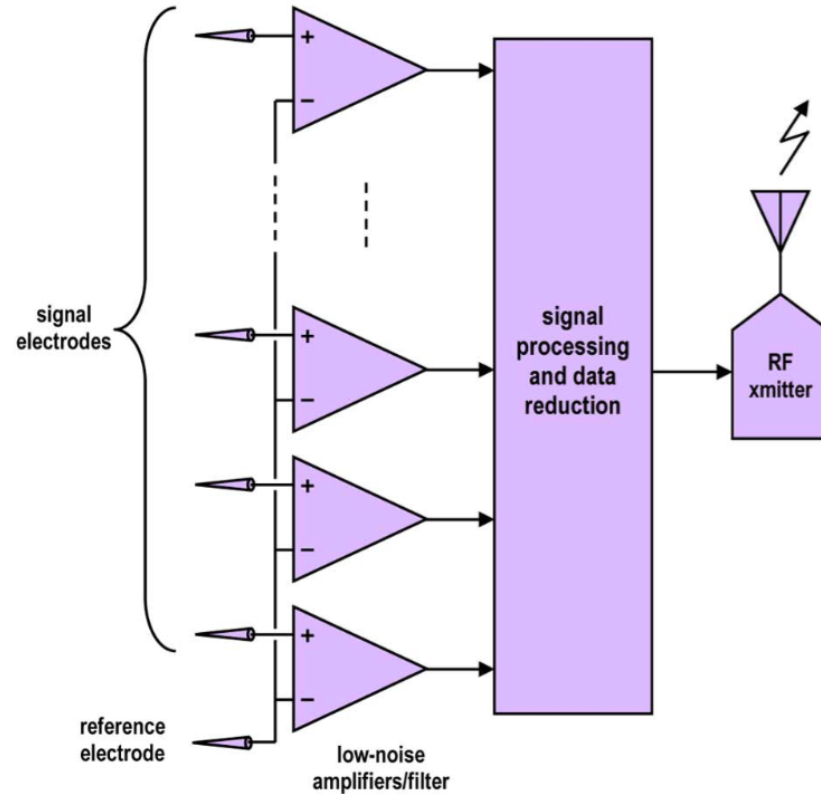
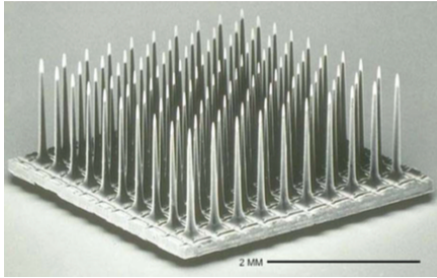
Intracortical systems



- Microchips include **amplification, filtering, digitization, compression, processing: feature extraction/spike detection/classification, wireless power and data telemetry, bias generation, stimulation, ...**
- Power and area are highly limited



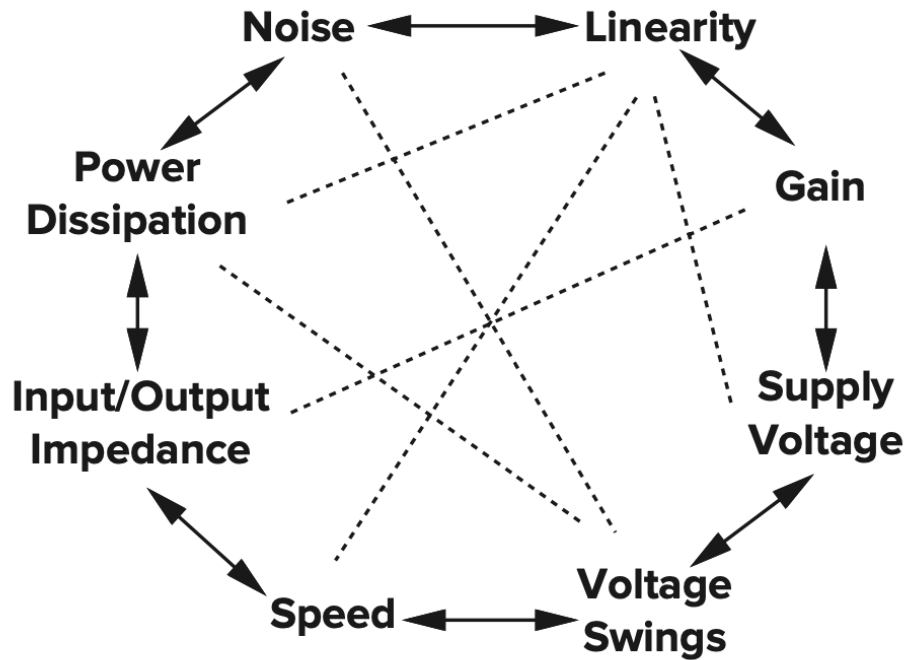
Die photo of 4.7 mm x 5.9 mm chip



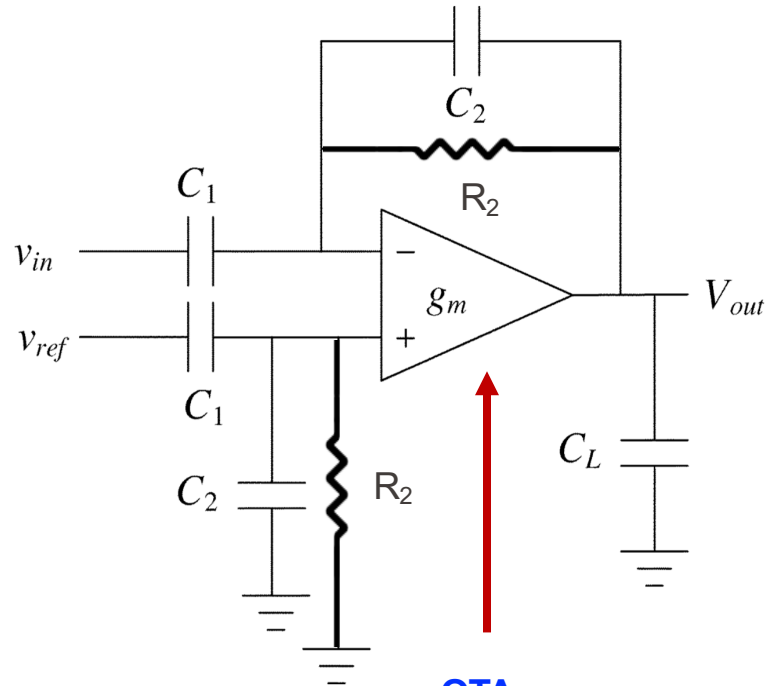
1. Sufficiently **low input-referred noise** to resolve spikes as small as $10\text{ }\mu\text{V}$ in amplitude
2. **Sufficient dynamic range** to record spikes or LFPs as large as $1\text{--}2\text{ mV}$ in amplitude
3. **Much higher input impedance** than the electrode-tissue interface
4. Amplify signals in the **frequency bands of interest** (roughly $300\text{ Hz--}10\text{ kHz}$ for spikes and $1\text{--}300\text{ Hz}$ for local field potentials)
5. **Block DC offsets** present at the electrode-tissue interface to prevent saturation of the amplifier

1. Sufficiently **low input-referred noise** to resolve spikes as small as 10 μV in amplitude
2. **Sufficient dynamic range** to record spikes or LFPs as large as 1–2 mV in amplitude
3. **Much higher input impedance** than the electrode-tissue interface
4. Amplify signals in the **frequency bands of interest** (roughly 300 Hz–10 kHz for spikes and 1–300 Hz for local field potentials)
5. **Block DC offsets** present at the electrode-tissue interface to prevent saturation of the amplifier
6. Consume **little silicon area** and use few or no off-chip components to minimize size
7. **High common-mode rejection ratio** to minimize interference from 50/60 Hz power line noise, and a **high power-supply rejection ratio** if power supply noise is significant (e.g., from ac inductive power links);
8. Consume **low power** to limit the chronic heating of surrounding tissue to less than 1°C.

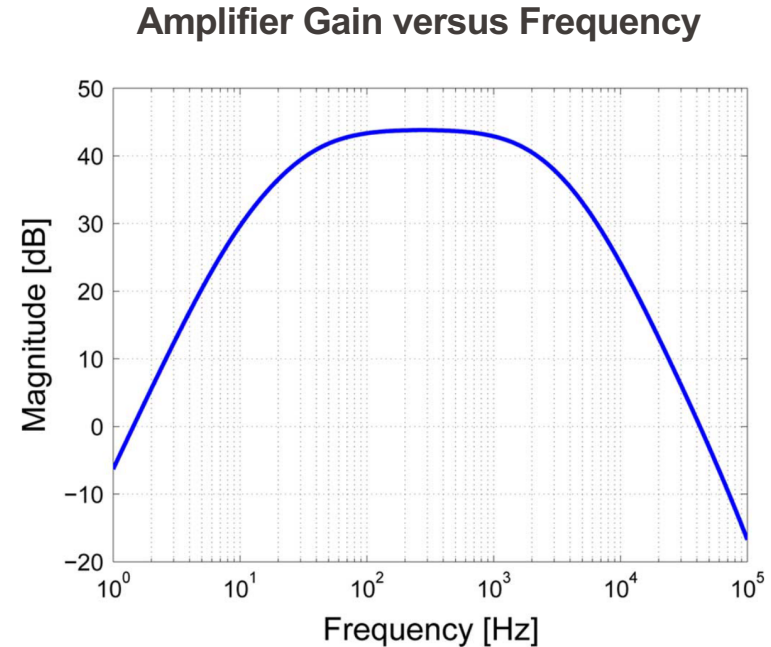
...



Neural Amplifier: Capacitive Feedback Architecture



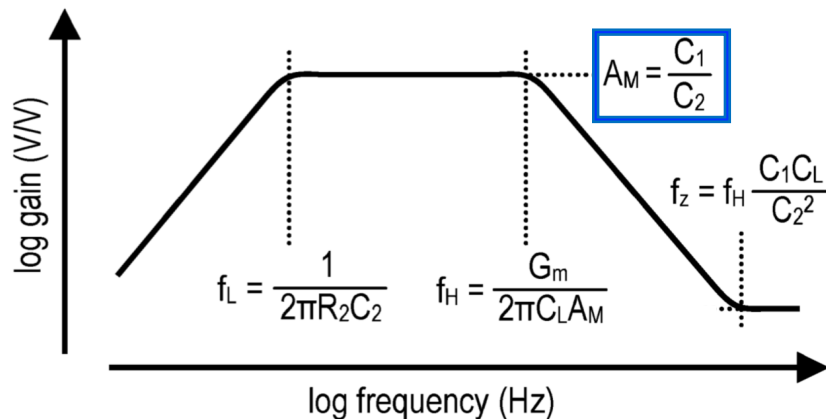
OTA:
Operational Transconductance Amplifier

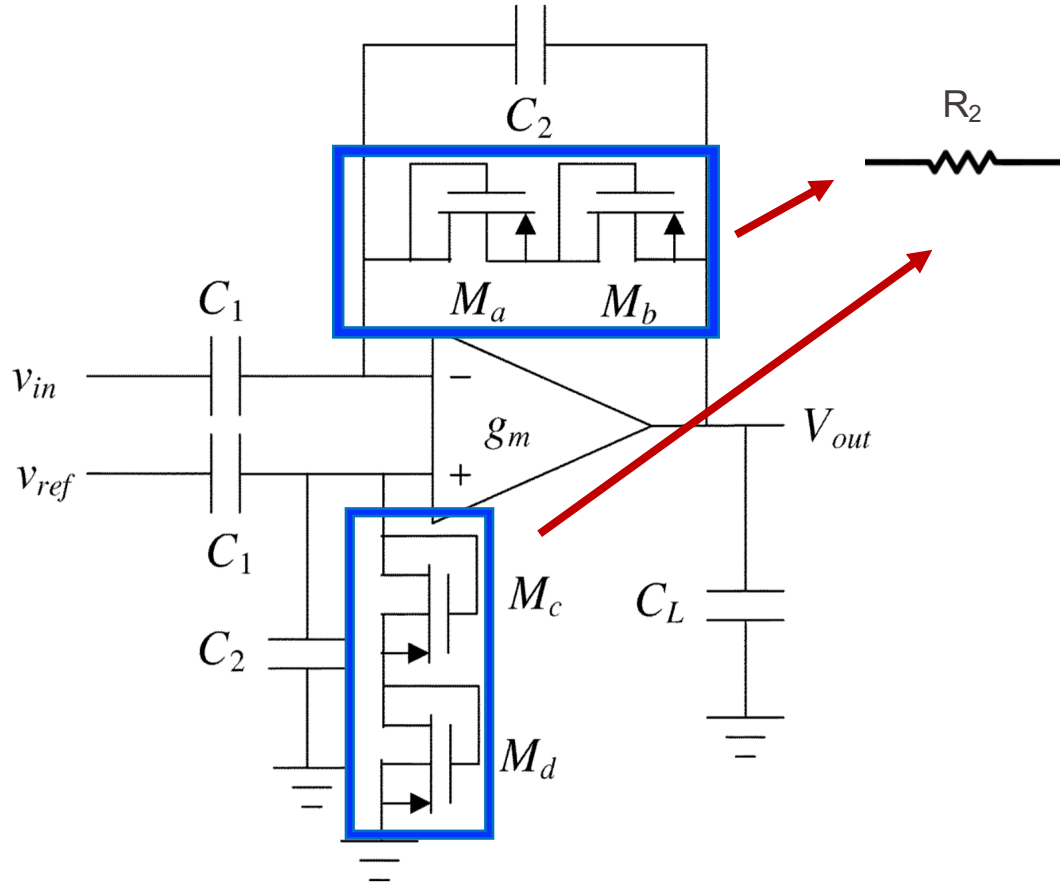


Neural Amplifier: Transfer Function

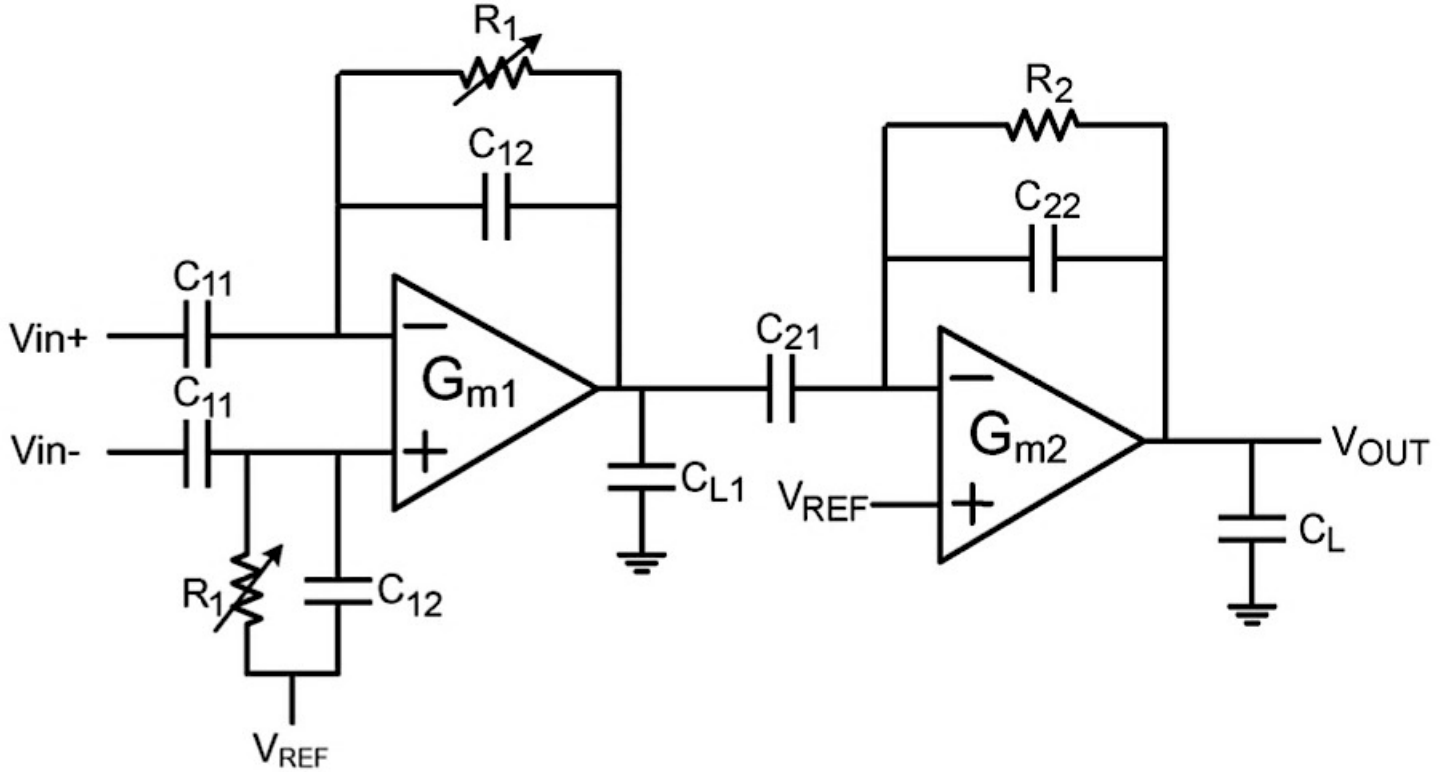
$$\frac{v_{\text{out}}}{v_{\text{in}+} - v_{\text{in}-}} = \frac{C_1}{C_2} \cdot \frac{1 - sC_2/G_m}{\left(\frac{1}{sR_2C_2} + 1\right) \left(s\frac{C_L C_1}{G_m C_2} + 1\right)}$$

$$= A_M \frac{1 - s/(2\pi f_z)}{\left(\frac{2\pi f_L}{s} + 1\right) \left(\frac{s}{2\pi f_H} + 1\right)}$$





Neural Amplifier: Multi-Stage, Higher Gain

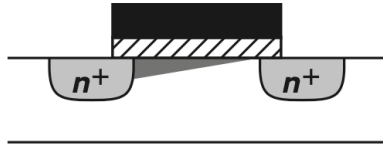


- A typical performance and comparison table

	[3] JSSC '09	[4] JSSC '07	[6] BioCAS '07	[7] ISSCC '10	[24] VLSI '11	This Work
Power (μW)	15	42.2	7.56	0.64	43	5.04
IRNoise (μV), Spike	7.0	5.1	3.06	14	2.2	4.9
Spike Bandwidth	5kHz	5kHz	5.3kHz	6.2kHz	10kHz	10kHz
NEF	4.6	9.8	2.67	6.5	5	5.99
NEF²•V_{DD}	63.48	316.9	20	33.8	30	17.96
IRNoise (μV), LFP	-	-	1.66*	-	14	4.3
LFP Bandwidth	-	-	300Hz*	-	100Hz	300Hz
CMRR (dB)	-	-	66	59	-	75
PSRR (dB)	-	-	75	71	-	64
V_{DD} (V)	3	3.3	2.8	0.8	1.2	0.5
Area (mm²)	0.04	0.16	0.16	0.4**	0.2**	0.013
Technology	0.35 μ m	0.5 μ m	0.5 μ m	0.13 μ m	0.13 μ m	65nm
Blocks included in comparison	LNA, BPF	LNA, BPF	LNA, BPF	LNA, BPF	LNA, BPF, ADC	LNA, BPF, ADC

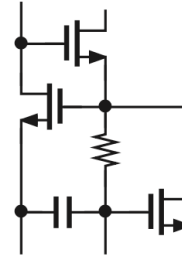
IC Design: Device, Circuit, Architecture, System

Device



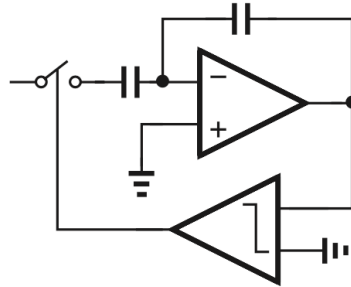
(a)

Circuit



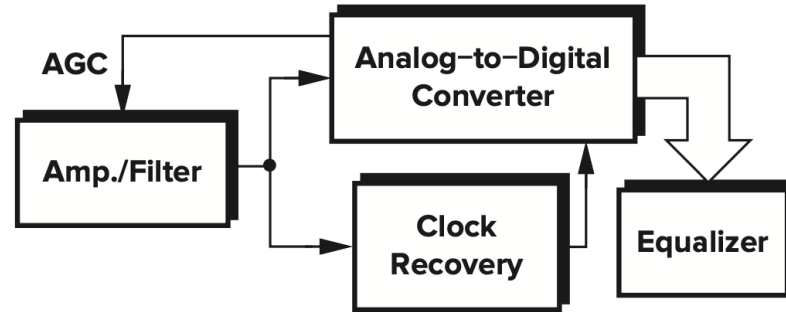
(b)

Architecture



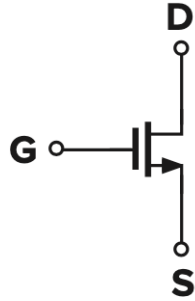
(c)

System



(d)

NMOS



$$I_D \approx \frac{1}{2} \mu_n C_{ox} \frac{W}{L} (V_{GS} - V_{TH})^2$$

- An n-type MOS (**NMOS**) device on a **p-type substrate**
 - a heavily-doped polysilicon (**conductor**) operating as the **gate**
 - a thin layer of silicon dioxide (SiO_2) **insulating** the gate from the substrate
 - two heavily-doped **n regions**: **source** and **drain** terminals

